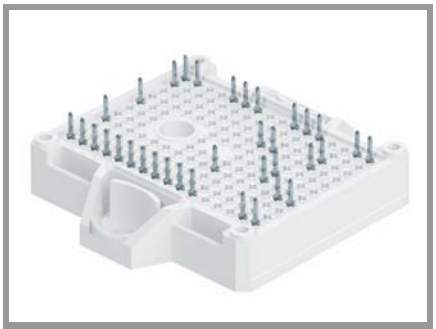
SK25DGD12T7ETE2s



SEMITOP®E2 Solder

3-phase Converter-Inverter (CI)

SK25DGD12T7ETE2s

Features*

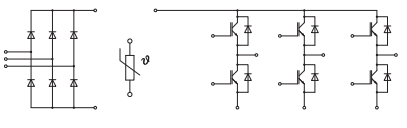
- Optimized design for superior thermal performance
- Low inductive design
- Solder contact technology
- 1200V Generation 7 IGBT (T7)
- Robust and soft switching CAL4F diode technology
- PEP rectifier diode technology for enhanced power and environmental robustness
- Integrated NTC temperature sensor
- UL recognized file no. E 63 532

Typical Applications

- Motor drives
- Air conditioning
- Auxiliary Inverters

Remarks

- Recommended $T_{j,op}$ = -40 ...+150 °C
- $T_{j,op}$ > 150 °C during overload (details in AN19-002)



DGD-ET

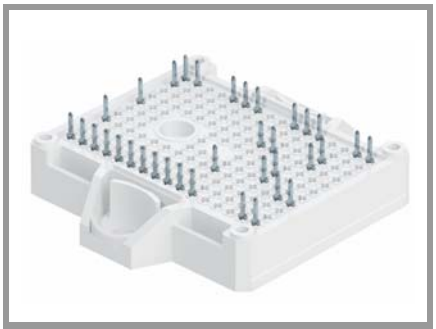
Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}			1200	V
I_C	P12 T_j = 175 °C	T_s = 70 °C	33	A
		T_s = 100 °C	27	A
I_C	HPTP / HP-PCM T_j = 175 °C	T_s = 70 °C	38	A
		T_s = 100 °C	31	A
I_{Cnom}			25	A
I_{CRM}			50	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V $V_{GE} \leq$ 15 V $V_{CES} \leq$ 1200 V	T_j = 175 °C	7	µs
T_j			-40 ... 175	°C
Inverse - Diode				
V_{RRM}	T_j = 25 °C		1200	V
I_F	P12 T_j = 175 °C	T_s = 70 °C	24	A
		T_s = 100 °C	20	A
I_F	HPTP / HP-PCM T_j = 175 °C	T_s = 70 °C	28	A
		T_s = 100 °C	23	A
I_{FRM}			50	A
I_{FSM}	t_p = 10 ms, sin 180°, T_j = 150 °C		100	A
T_j			-40 ... 175	°C
Rectifier - Diode				
V_{RRM}	T_j = 25 °C		1600	V
I_F	P12 T_j = 175 °C	T_s = 70 °C	47	A
		T_s = 100 °C	37	A
I_F	HPTP / HP-PCM T_j = 175 °C	T_s = 70 °C	57	A
		T_s = 100 °C	45	A
I_{FSM}	t_p = 10 ms sin 180°	T_j = 25 °C	370	A
		T_j = 150 °C	270	A
i^2t	t_p = 10 ms sin 180°	T_j = 25 °C	685	A^2s
		T_j = 150 °C	365	A^2s
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$	, $\Delta T_{terminal}$ at PCB joint = 30 K, per pin		30	A
T_{stg}	module without TIM		-40 ... 125	°C
V_{isol}	AC, sinusoidal, 1 min		2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	I_C = 25 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.60	1.75	V
		T_j = 150 °C		1.78	1.93	V
		T_j = 175 °C		1.82	1.97	V
V_{CE0}	chiplevel	T_j = 25 °C		1.00	1.05	V
		T_j = 150 °C		0.80	0.85	V
		T_j = 175 °C		0.75	0.80	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		24	28	mΩ
		T_j = 150 °C		39	43	mΩ
		T_j = 175 °C		43	47	mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE}$, I_C = 0.53 mA		5.15	5.8	6.45	V

SK25DGD12T7ETE2s



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Typical Applications

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Remarks

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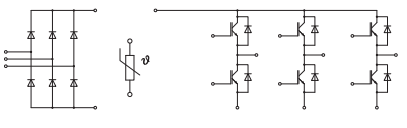
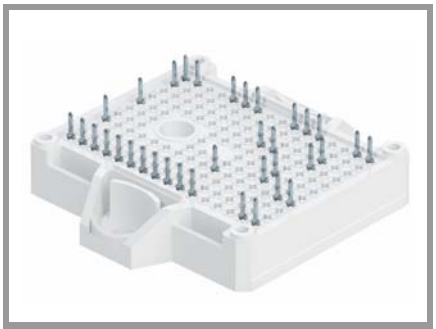


DGD-ET

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C				1	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		4.80		nF
C_{oes}		f = 1 MHz		0.06		nF
C_{res}		f = 1 MHz		0.02		nF
Q_G	V_{GE} = -15 V ... +15 V			354		nC
R_{Gint}	T_j = 25 °C			0		Ω
$t_{d(on)}$	V_{CC} = 600 V I_C = 25 A $R_{G\,on}$ = 6.2 Ω $R_{G\,off}$ = 6.2 Ω V_{GE} = +15/-15 V (T_j = 150 °C) di/dt_{on} = 880 A/µs di/dt_{off} = 210 A/µs dv/dt = 5400 V/µs	T_j = 25 °C		28		ns
		T_j = 150 °C		30		ns
		T_j = 175 °C		32		ns
t_r		T_j = 25 °C		23		ns
		T_j = 150 °C		25		ns
		T_j = 175 °C		26		ns
E_{on}		T_j = 25 °C		1.65		mJ
		T_j = 150 °C		2.42		mJ
		T_j = 175 °C		2.72		mJ
$t_{d(off)}$		T_j = 25 °C		191		ns
		T_j = 150 °C		231		ns
		T_j = 175 °C		251		ns
t_f		T_j = 25 °C		66		ns
		T_j = 150 °C		101		ns
		T_j = 175 °C		108		ns
E_{off}		T_j = 25 °C		2.04		mJ
		T_j = 150 °C		2.71		mJ
		T_j = 175 °C		3.09		mJ
$R_{th(j-s)}$	per IGBT, P12 (Reference)			1.32		K/W
$R_{th(j-s)}$	per IGBT, HPTP / HP-PCM			1.06		K/W
Inverse - Diode						
$V_F = V_{EC}$	I_F = 25 A chiplevel	T_j = 25 °C		2.41	2.74	V
		T_j = 150 °C		2.45	2.79	V
		T_j = 175 °C		2.30	2.62	V
V_{F0}	chiplevel	T_j = 25 °C		1.30	1.50	V
		T_j = 150 °C		0.90	1.10	V
		T_j = 175 °C		0.82	0.98	V
r_F	chiplevel	T_j = 25 °C		44	50	mΩ
		T_j = 150 °C		62	68	mΩ
		T_j = 175 °C		59	66	mΩ
I_{RRM}	I_F = 25 A V_{GE} = -15 V V_{CC} = 600 V (T_j = 150 °C) di/dt_{off} = 1050 A/µs	T_j = 25 °C		20		A
		T_j = 150 °C		28		A
		T_j = 175 °C		30		A
Q_{rr}		T_j = 25 °C		1.41		µC
		T_j = 150 °C		3.71		µC
		T_j = 175 °C		4.19		µC
E_{rr}		T_j = 25 °C		0.51		mJ
		T_j = 150 °C		1.61		mJ
		T_j = 175 °C		2.46		mJ
$R_{th(j-s)}$	per Diode, P12 (Reference)			1.66		K/W
$R_{th(j-s)}$	per Diode, HPTP / HP-PCM			1.29		K/W

SK25DGD12T7ETE2s



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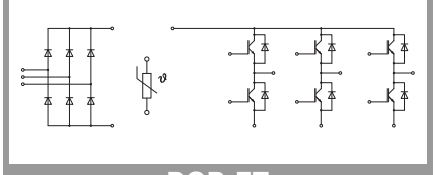


DGD-ET

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Rectifier - Diode						
$V_F = V_{EC}$	I_F = 25 A chiplevel	T_j = 25 °C		1.04	1.30	V
		T_j = 150 °C		0.95	1.21	V
		T_j = 175 °C		0.94	1.21	V
V_{F0}	chiplevel	T_j = 25 °C		0.89	1.09	V
		T_j = 150 °C		0.73	0.92	V
		T_j = 175 °C		0.69	0.88	V
r_F	chiplevel	T_j = 25 °C		6.2	8.5	mΩ
		T_j = 150 °C		8.8	12	mΩ
		T_j = 175 °C		10.0	13	mΩ
I_R	T_j = 150 °C, V_{RRM}				2	mA
$R_{th(j-s)}$	per Diode, P12 (Reference)			1.48		K/W
$R_{th(j-s)}$	per Diode, HPTP / HP-PCM			1.14		K/W
Module						
M_s	to heatsink		1.6		2.3	Nm
w				35		g
L_{CE}				30		nH
Temperature Sensor						
R_{100}	T_c=100°C (R_{25}=5 kΩ)			493 ± 5%		Ω
$B_{25/85}$	$R_{(T)}=R_{25}*\exp[B_{25/85}*(1/T-1/298)]$, T[K]			3420		K

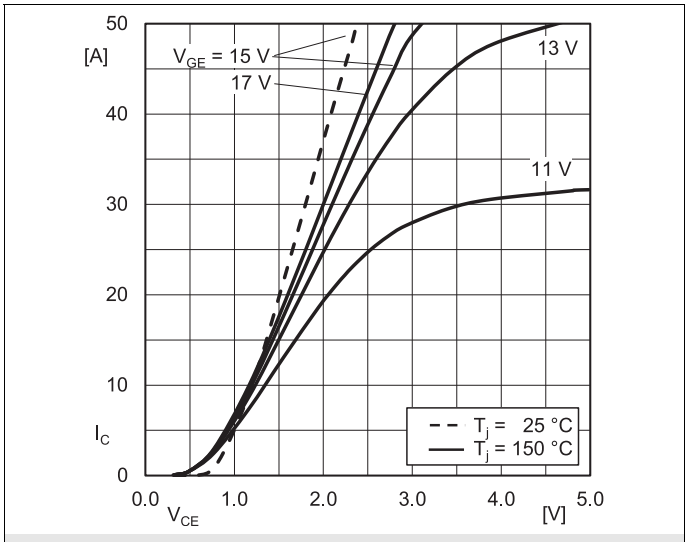


Fig. 1: Typ. IGBT output characteristic, incl. $R_{CC+\ EE'}$

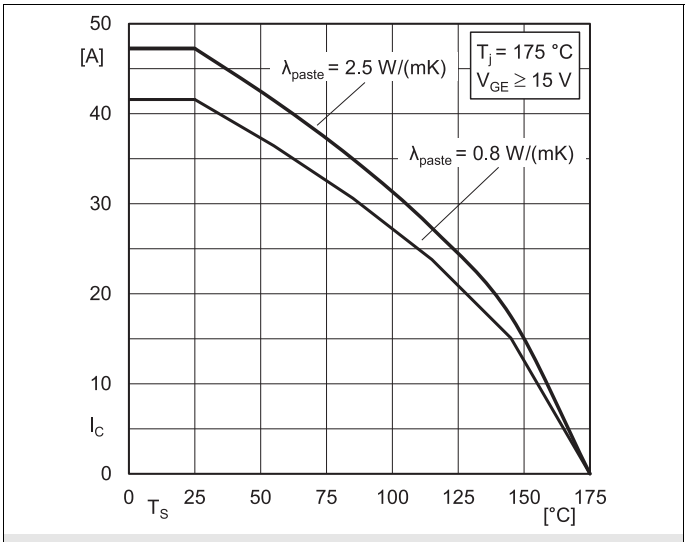


Fig. 2: IGBT rated current vs. temperature $I_c=f(T_s)$

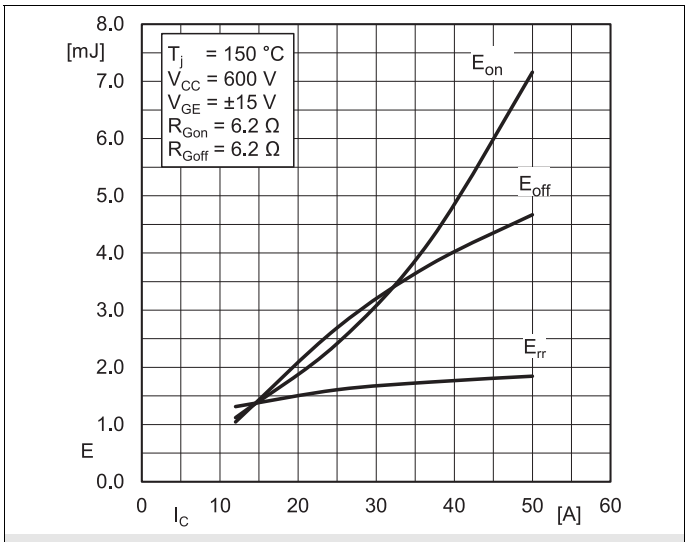


Fig. 3: Typ. turn-on /-off energy = f (I_C)

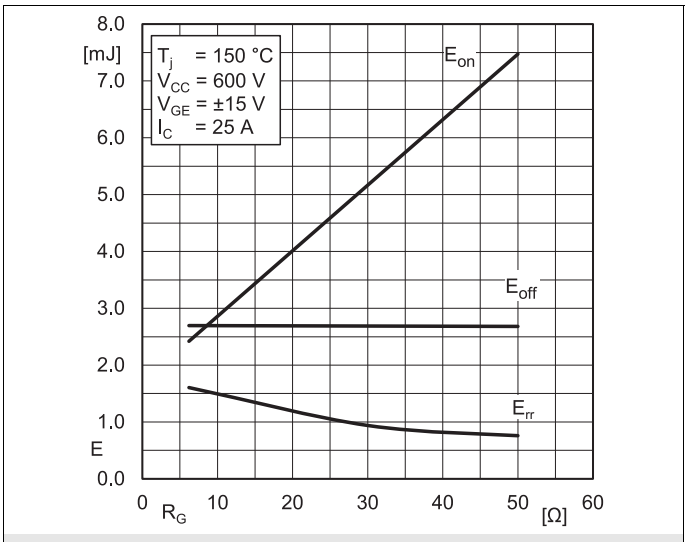


Fig. 4: Typ. turn-on /-off energy = f (R_G)

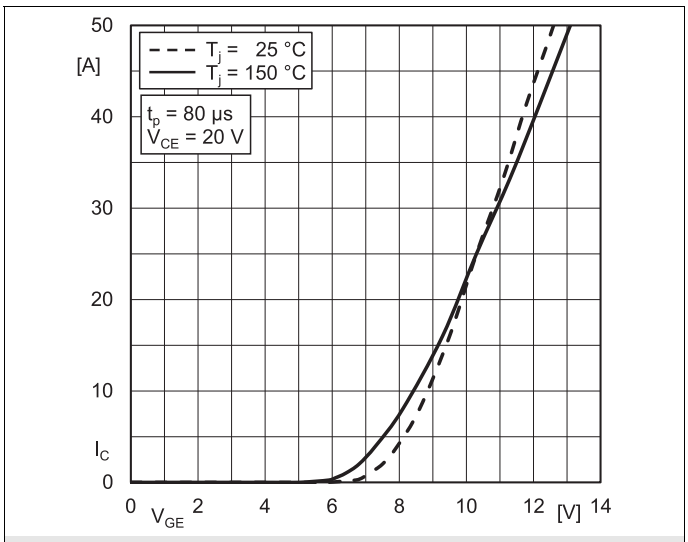


Fig. 5: Typ. IGBT transfer characteristic

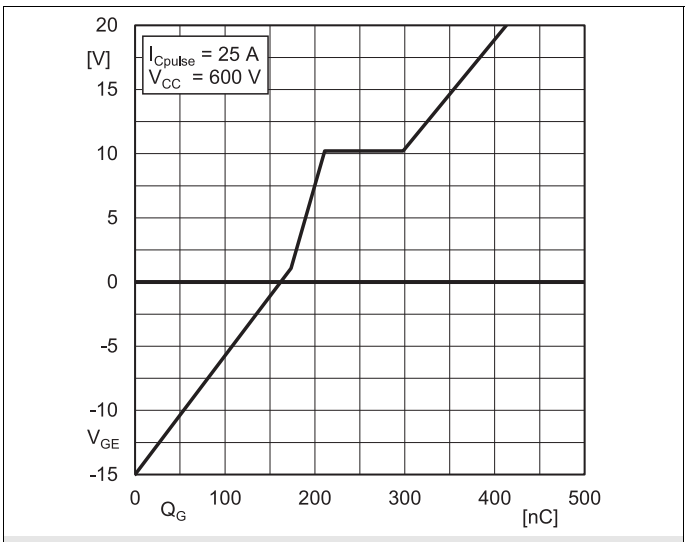


Fig. 6: Typ. IGBT gate charge characteristic

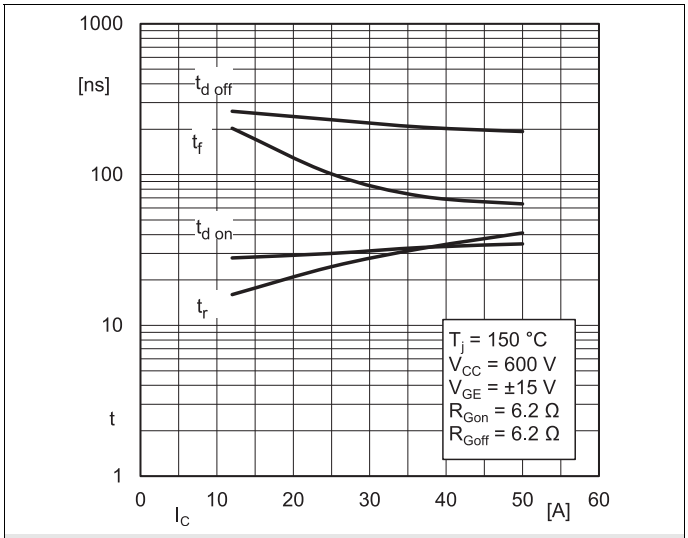


Fig. 7: Typ. switching times = f (I_C)

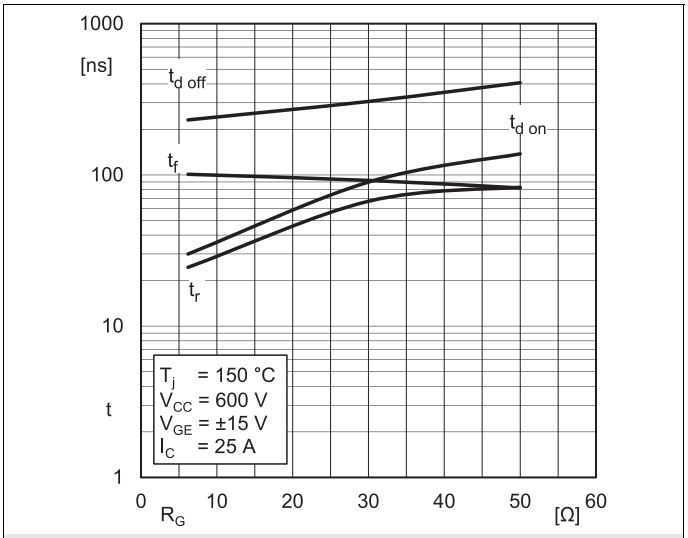


Fig. 8: Typ. switching times = f (R_G)

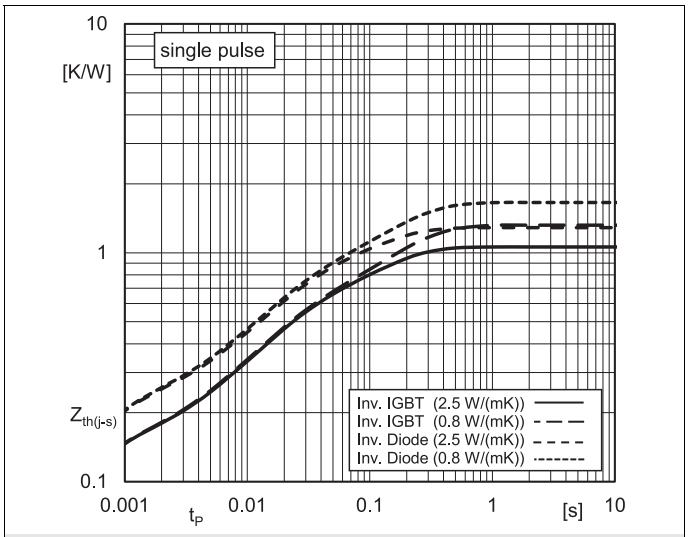


Fig. 9: Typ.transient thermal impedance

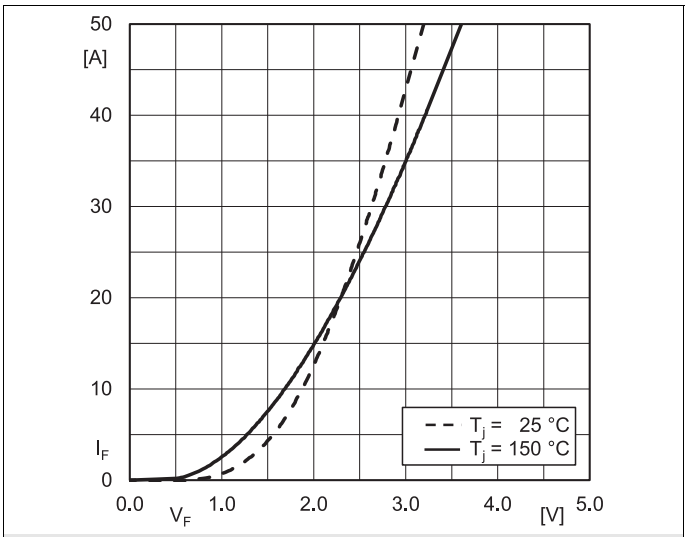


Fig. 10: Typ. Inv. diode forward charact., incl. $R_{CC'+EE'}$

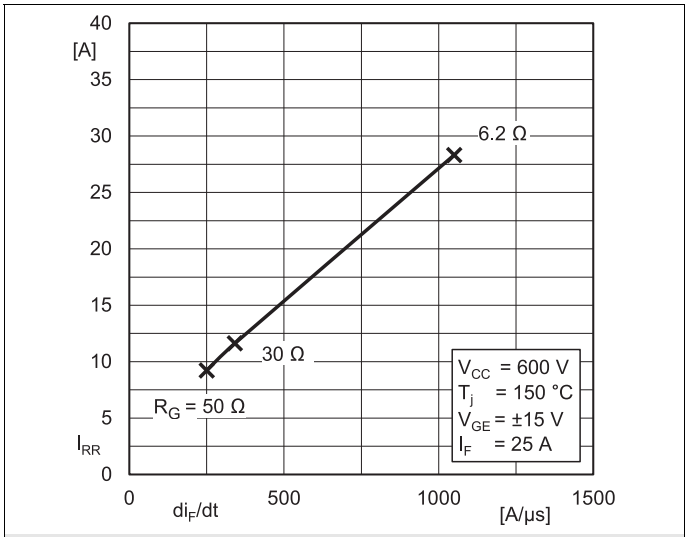


Fig. 11: Typ. Inv. diode peak reverse recovery current

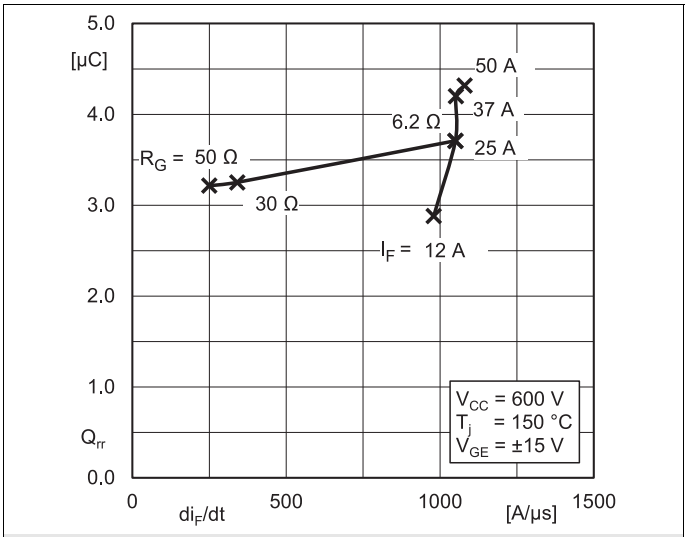


Fig. 12: Typ. Inv. diode reverse recovery charge

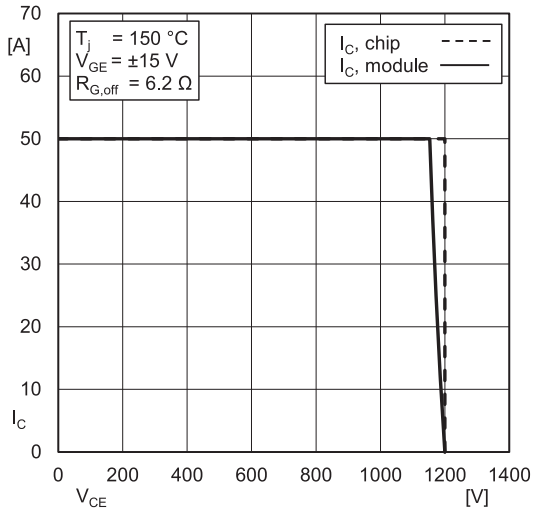


Fig. 13: IGBT Reverse Bias Safe Operating Area (RBSOA)

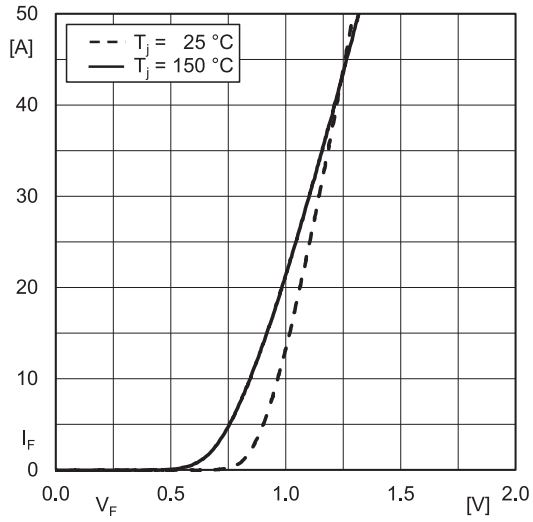
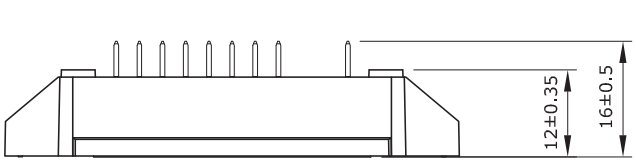
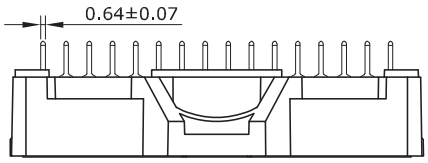
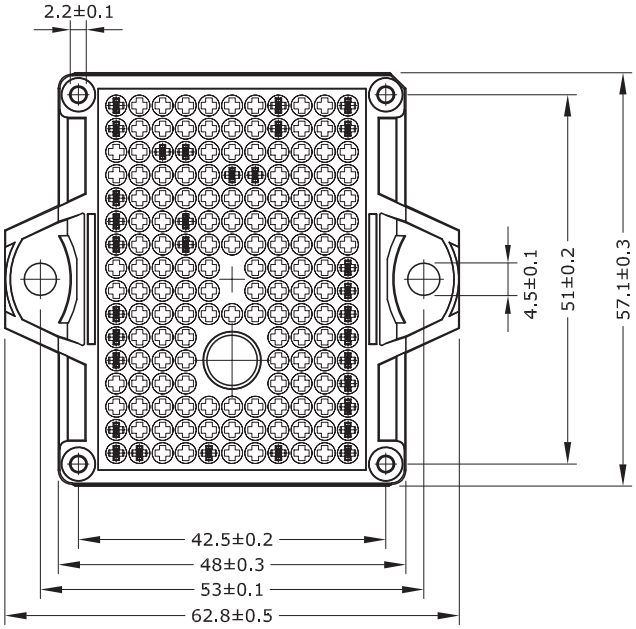
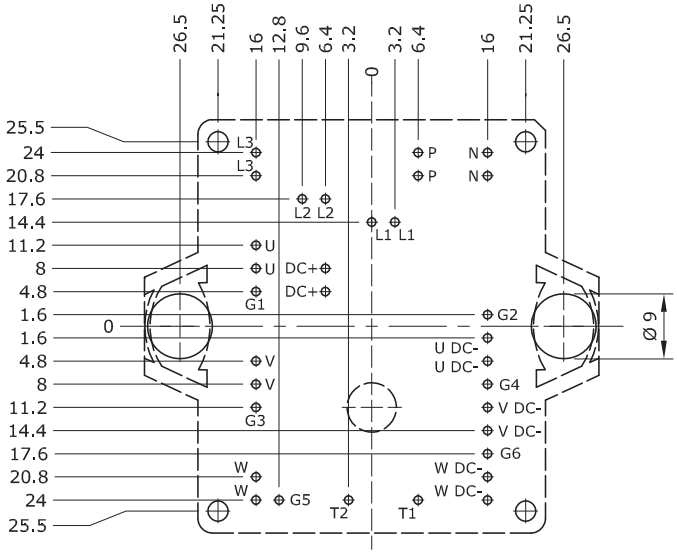


Fig. 14: Typ. Rect. diode forward charact., incl. $R_{CC'+EE'}$



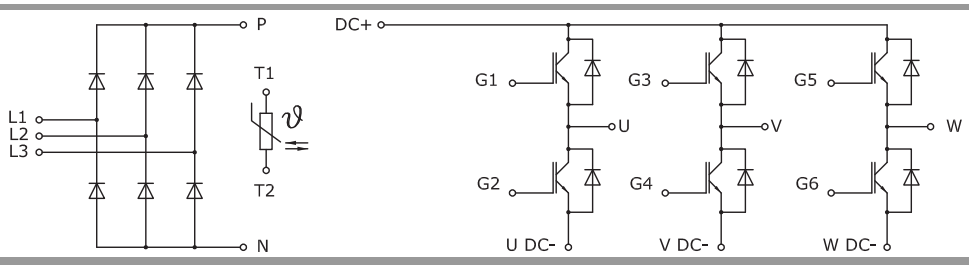






- Pin-Grid 3.2 mm
- Tolerance of pinpositions ⌖ | Ø0.4

SEMITOP®E2 Solder



DGD-ET

IMPORTANT INFORMATION AND WARNINGS

This is an electrostatic discharge sensitive device (ESDS) according to international standard IEC 61340.

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